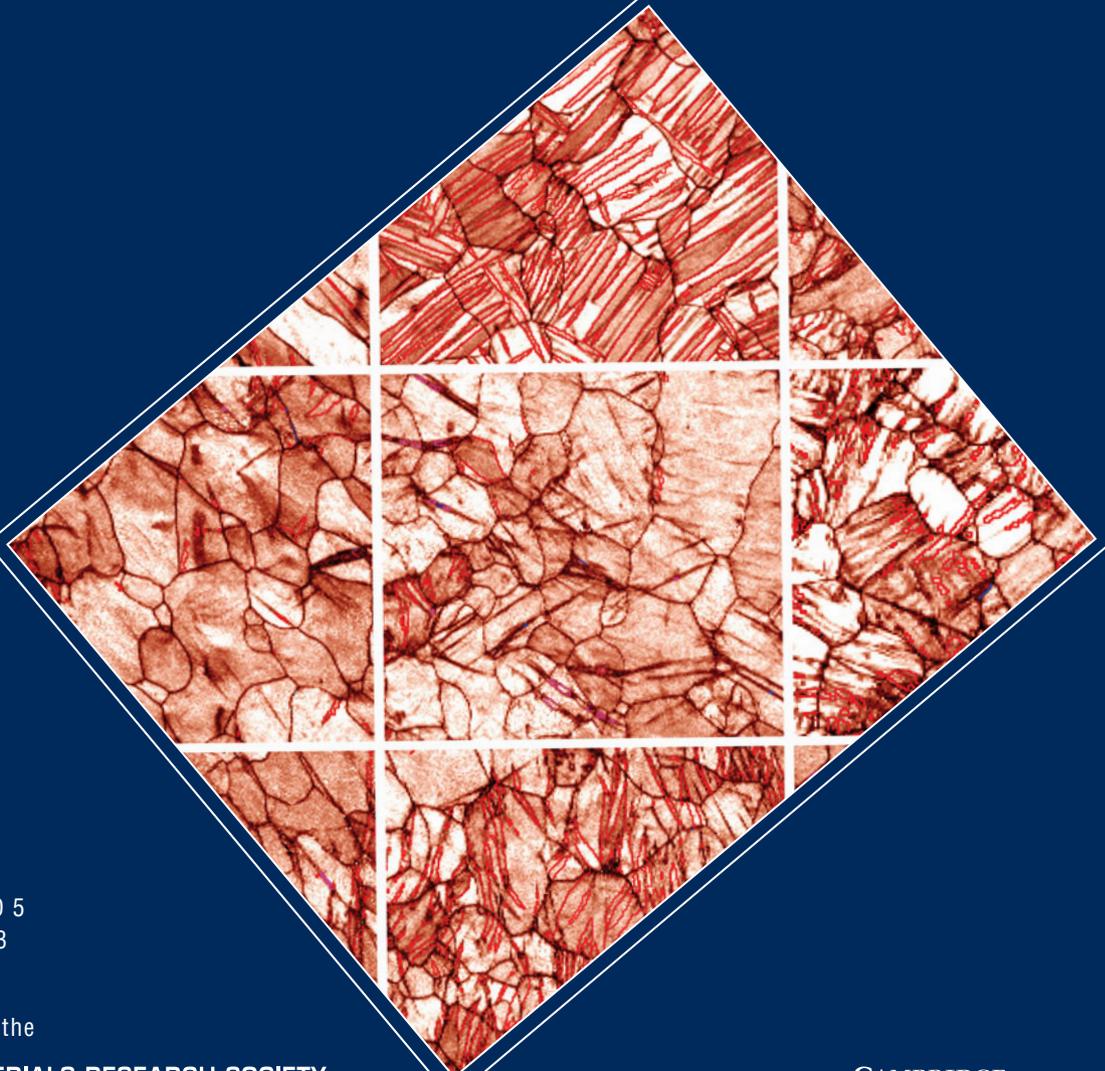




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Journal of MATERIALS RESEARCH

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Cover: EBSD micrographs illustrating the microstructure evolution of pre-deformed AZ31 samples after 0° and 90° tension. [C. Lou, X.Y. Zhang, R.H. Wang, and Q. Liu: Mechanical behavior and microstructural characteristics of magnesium alloy containing {10-12} twin lamellar structure. p. 733.]

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